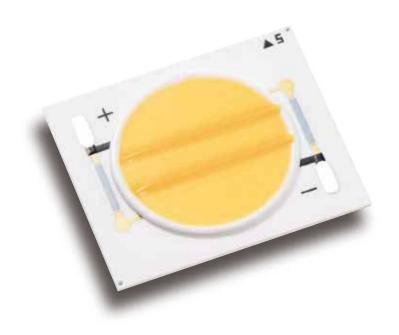


SPECIFICATIONS

Mega Zenigata with Natural Toning

GW6TGBJC50C

 $2000K \sim 3000K$



ZENIGATA

Notice

Contents in this technical document be changed without any notice due to the product modification. In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that may occur in wquipment using any SHARP devices shown in catalogs, data books, etc.

LIGHTING BUSINESS UNIT
ELECTRONIC COMPONENTS AND DEVICES BU
SHARP CORPORATION



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- (1)Please do verify the validity of this part after assembling it in customer's products, when customer wants to make catalogue and instruction manual based on the specification sheet of this part.
- (2)The products covered herein are designed and manufactured for the following application areas. When using the products covered herein for the equipment listed in paragraph (3), even for the following application areas, be sure to observe the precautions given in Paragraph (3). Never use the products for the equipment listed in Paragraph (4).
- *Office electronics
- *Instrumentation and measuring equipment
- *Machine tools
- *Audiovisual equipment
- *Home appliances
- *Communication equipment other than for trunk limes
- (3)These contemplating using the products covered herein for the following equipment which demands high reliability, should first contact a sales representative of the company and then accept responsibility for incorporating into the design fail-safe operation, redundancy, and other appropriate measures for ensuring reliability and safety of the equipment and the overall system.
- *Control and safety devices for airplanes, trains, automobiles, and other transportation equipment
- *Mainframe computers
- *traffic control systems
- *Gas leak detectors and automatic cutoff devices
- *Rescue and security equipment
- *Other safety devices and safety wquipment, etc.
- (4)Do not use the products covered herein for the following equipment which demands extremely high performance in terms of functionality, or accuracy.
- *Aerospace equipment
- *Communications equipment for trunk lines
- *Control equipment for the nuclear power industry
- *Medical equipment related to life support, etc.
- (5)please direct all queries and comments regarding the interpretation of the above four Paragraphs to a sales representative of the company.
- Please direct all queries regarding the products covered herein to a sales representative of the company.

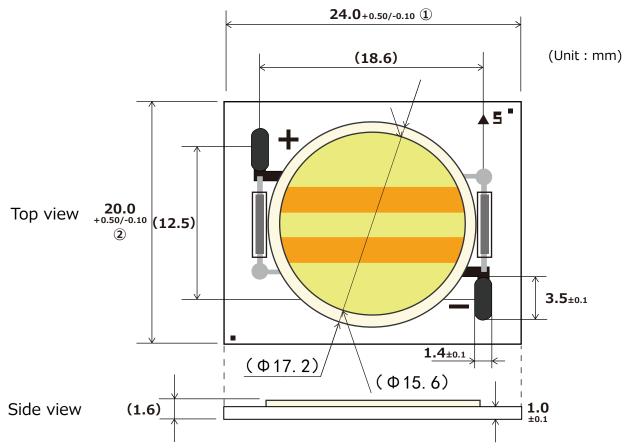


GW6TGBJC50C Specifications

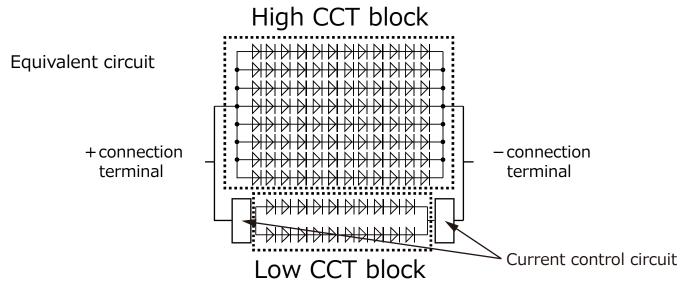
 Application These specifications apply to the light emitting did [LED module (InGaN Blue LED chip + Phosphor) Main application : Lighting 	
2. External dimensions and equivalent circuit ———	Refer to Page 2.
3. Ratings and characteristics —	Refer to Page 3-6.
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4. Reliability —	Refer to Page 7.
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5. Quality level —	Refer to Page 8.
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2. External dimensions and equivalent circuit



(Note) Values inside parentheses are reference values. External sizes of ①、② are determined by maximum dimensions, that include salient areas on the edges of respective sides.



High CCT block 12 series \times 8 parallel = 96 pcs of LEDs Low CCT block 10 series \times 2 parallel = 20 pcs of LEDs

Unit	Material	Drawing No.
mm	Substrate : Alumina Ceramic	52605044



3. Ratings and characteristics

3-1. Absolute maximum ratings

Item	Symbol	Rating	Unit
Power Dissipation (※1,4)	Р	P 41.6	
Forward Current (%1,4)	I_{F}	1 050	mA
Reverse Voltage (%2,4)	e (%2,4) VR -15		V
Operating Temperature (※3)	Topr	-30 ~ +100	$^{\circ}$
Storage Temperature	Tstg	-40 ~ +100	$^{\circ}$
Junction Temperature	Tj	145	$^{\circ}$

^{*1} Power dissipation and forward current are the values when the module temperature is set lower than the rating by using an adequate heat sink.

(Not dealing with the possibility of always-on reverse voltage.)

^{*2} The maximum rating of reverse voltage is assumed, after considering the voltage that occur due to initial connection error that may occur suddenly.

^{*3} Operating temperature is the Case temperature Tc (Refer to measuring point for case temperature in the next page.)
Refer to "Derating curve" in the next page as for operating current.

^{*4} Tc = 25℃



3-2. Electro-optical characteristics

(Tj=25℃)

ССТ	Item	Symbol	Condition	MIN.	TYP.	MAX.	Unit
	Forward Voltage ※5	V _F		25.8	(30.4)	33.4	V
	Luminous Flux ※ 6	Φ	$I_F = 80 \text{mA}$	120	(155)	-	lm
2000K	Chromaticity	Х	15 -00111/1	-	(0.5251)	1	-
	Coordinates ※ 7	У		1	(0.4120)	1	-
	General Color Rendering Index 8	Ra		90	(94)	-	-
	Forward Voltage ※5	V_{F}		30.5	(35.8)	39.6	V
	Luminous Flux ¥ 6	Φ	I _F =950mA	2430	(2860)	1	lm
3000K	Chromaticity Coordinates※ 7	Х	1F = 330111A	1	(0.4370)	1	-
		У		-	(0.4030)	-	-
	General Color Rendering Index **8	Ra		90	(92)	-	-

(Note) Values inside parentheses are shown for reference purpose only.

^{*5 (}After 5 ms drive, Measurement tolerance: ± 3 %)

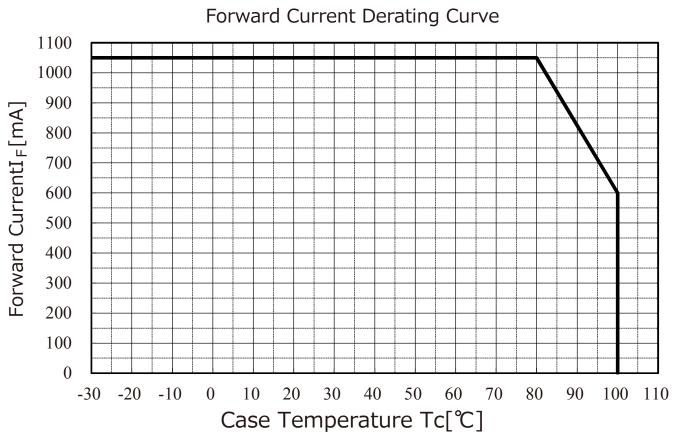
 $^{^*}$ 6 Monitored by Sharp's 1m integrating sphere and Otsuka electronics SR-2000A (After 5 ms drive, Measurement tolerance: \pm 10 %)

^{*7} Monitored by Sharp's 1m integrating sphere and Otsuka electronics SR-2000A (After 5 ms drive, Measurement tolerance: \pm 0.005)

^{*8} Monitored by Sharp's 1m integrating sphere and Otsuka electronics SR-2000A (After 5 ms drive, Measurement tolerance: \pm 2)



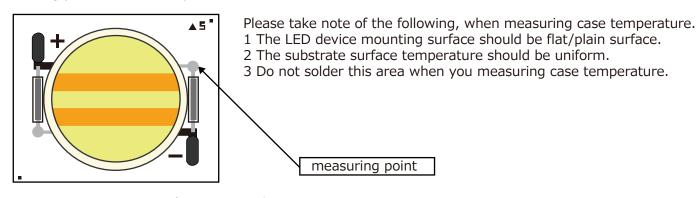
3-3. Derating curve



(Note) To keep the case temperature lower than the rating, enough heat-radiation performance needs to be secured by using an adequate heat sink.

For soldering connection, please evaluate in your circumstance to make sure soldering reliability. (Above derating curve is specified to LED device, not for soldering connection) And please consider to avoid physical stress between wire and substrate, and some protection like silicon bond on top of soldered wire is recommended. Please ensure the maintenance of heat radiation not to exceed case temperature over the rating in operation.

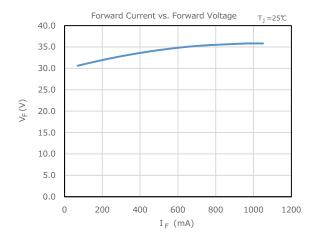
(Measuring point for case temperature)

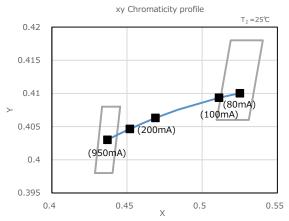


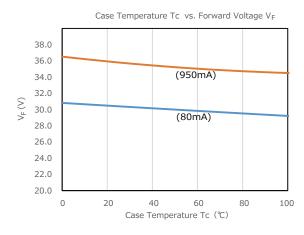
Thermal Resistance : 1.30℃/W (Typical value)

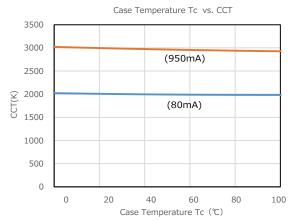


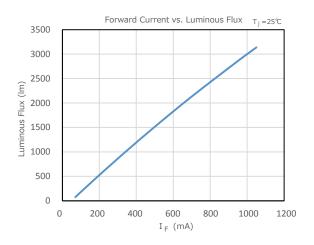
3-4. Characteristics diagram (TYP.)

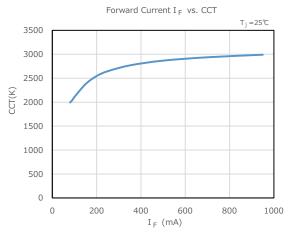


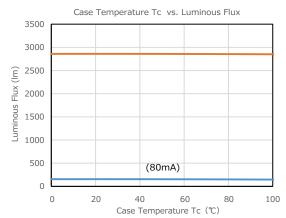


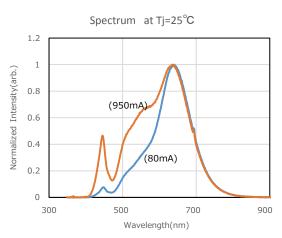














4. Reliability

The reliability of products shall be satisfied with items listed below.

4-1. Test items and test conditions

Confidence level: 90%

No.	Test item	Test conditions	samples n	Defective C	LTPD (%)
1	Temperature Cycle	- 40 $^{\circ}$ C(30 min) \sim + 100 $^{\circ}$ C(30 min), 100 cycles	11	0	20
2	Temperature Humidity Storage	Tstg = $+$ 60 °C, RH = 90 %, Time = 1000 h	11	0	20
3	High Temperature Storage	Tstg = + 100℃, Time = 1000 h	11	0	20
4	Low Temperature Storage	Tstg = - 40 ℃, Time = 1000 h	11	0	20
5	Steady State Operaring Life	Tc = 80 °C, $I_F = 950$ mA, Time = 1000 h	11	0	20
6	Shock	Acceleration: 15000 m/s ² , Pulse width: 0.5 ms Direction: 3 directions (X, Y and Z) 3 trials in each direction	5	0	50
7	Vibration	Frequency: 100 to 2000 Hz for 4 minutes per trial Acceleration: 200 m/s ² Direction: 3 directions (X, Y and Z) 4 trials in each direction	5	0	50

4-2. Failure criteria

No.	Parameter	Symbol	Failure criteria
1	Forward Voltage	V _F	V _F > Initial value×1.1
2	Luminous Flux	Φ	ϕ <initial td="" value×0.7<=""></initial>



5. Quality level

- 5-1.Applied standard (ISO2859-1)
- 5-2. Sampling inspection (A single normal sampling plan, level S-4)
- 5-3.Inspection items and defect criteria

No.	Item	Defect criteria	Classification	AQL		
1	No radiation	No light emitting	Major	0.1		
		J J	defect			
2	Electro-optical	Not conforming to the specification				
	characteristics	(Forward voltage, Luminous flux and Chromaticity values)				
3	External	Not conforming to the specification				
	dimensions	the seminary of the speciments				
	Appearance	Nonconformity observed in product appearance is determined	Minor			
		as defective only when electro-optical characteristics is affected by.	defect	0.4		
		<if above="" any="" arises="" criterion="" mentioned="" of="" question="" regardless=""></if>	0.0.00			
4		■ Foreign material,scratch, or bubble at emitting area:0.8mm				
		■ Fiber generation at emitting area:0.2mm ib width and 2.5mm inlengh				
		■ Foreign material at connection terminal:0.8mmΦ				
		■Substrate burr on edge:Over dimension tolerance				

(Note) Products with removable foreign material attached on is not determined to be defective.



6. Supplements

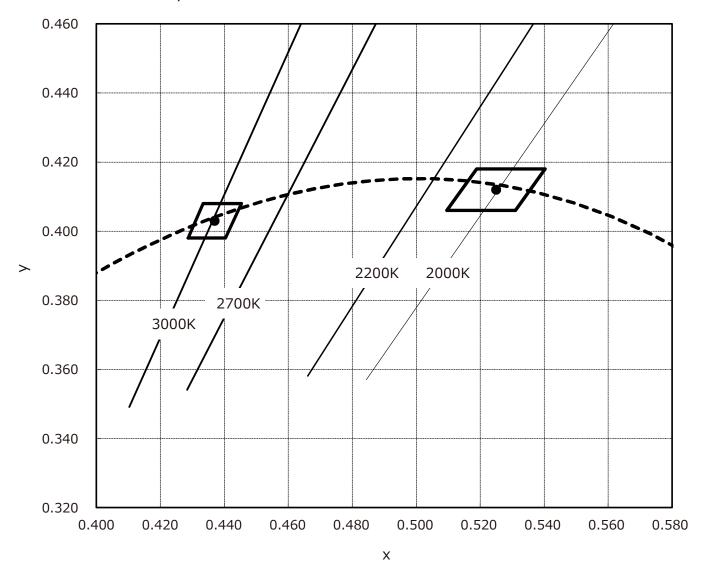
6-1.Chromaticity rank table (Tolerance : $x,y\pm0.005$)

(Tj=25℃)

	ank		Chromaticity coordinates			
Rank			Point 1	Point 2	Point 3	Point 4
	2 000K	X	0.5097	0.5311	0.5404	0.5190
1	$(I_F=80\text{mA})$	У	0.4060	0.4060	0.4180	0.4180
1	3 000K	X	0.4287	0.4404	0.4454	0.4334
	(I _F =950mA) y		0.3980	0.3980	0.4080	0.4080

Chromaticity Diagram

---- Black Body curve





6-2.Packing

- One tray composed of 40 pieces
- 5 trays(200 piecies)and one upper lid-tray in one moisture-proof bag
- 2 bags(400 pieces) in one carton
- Dimensions of outer carton:235×220×90mm (Reference value)
 (Note 1)Thre are cases of one carton composed of one bag (200 pieces)
 (Note 2) State of packing is dubject to change.

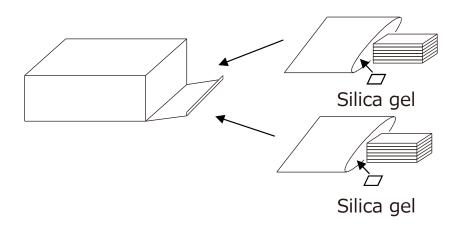
<Outer carton>

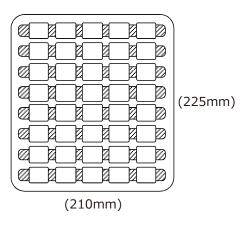
<One bag>

<One tray>

200 pieces × 2 bags = 400 pieces × 40 pieces × 5 trays = 200 pieces

 $5 \times 8 = 40$ pieces





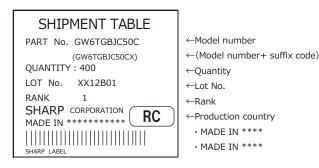


6-3.Label

1) Outer carton

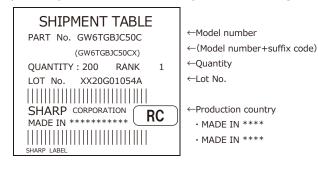
Following label is attached on outer carton.

(Note 3) Label format is subjected to change.



2) Moisture-Proof bag

Following label is attached on moisture-proof bags. (Note 3) Label format is subjected to change.



· Lot No.indication

XX 11 B 25 ① ② ③ ④

- ①Production plant code
- ②Shipping year (Year last 2 digits)
- ③Shipping month (from january to Doccmber in ABC order)
- 9Shipping date (01 \sim 31) NNotation may be different
- · Lot No.indication

XX	1	9	G	11	123	Α
1	2	3	4	(5)	6	7

- ①Production plant code
- ②Shipping year (Year last digit)
- ③Shipping month $(1 \sim 9 \text{ or O,N,D})$
- 4 Fixed code G
- ⑤Shipping date $(01 \sim 31)$
- 6 Serial No.
- ⑦Backup code A
 - ※Notation may be different

6-4. Indication printed on product

Model No. and control No. are indicated on substrate surface.

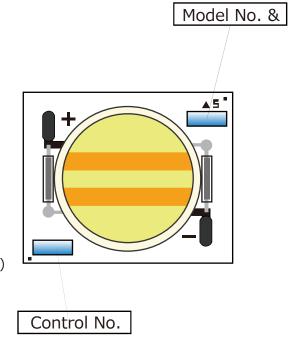
1) Model No. & Rank:

1st line: Abbreviated Model No 'GBJCC' is indicated." 2nd line: Rank:

2) Control No. Indicated as follows;

12 B 11 ① ② ③

- ① Year of production (the last two figures of the year)
- ② Month of production (to be indicated alphabetically with January corresponding to A)
- 3 Date of production (01 \sim 31)





7. Precautions

① Storage conditions

Please follow the conditions below.

• Before opend: Temperature $5 \sim 30^{\circ}$ C, Relative humidity less than 60%.

(Before opened LED should be used within a year)

• After opened: Temperature $5 \sim 30^{\circ}$ C, Relative humidity less than 60%.

(Please apply soldering within 1 week)

· Avoid exposing to air with corrosive gas.

If exposed, electrode surface would be damaged, which may affect soldering.

② Usage conditions

This product is not designed for use under any of the following conditionds.

Pleasecarefully check the performance and reliability well enough in case of using under any of the following conditions;

- In a please with a lot of moisture, dew condensation, briny air, and corrosive gas. (CL, H2S, NH3, SO2, NOX, etc)
- Under the direct sumlight, outdoor exposure, and in a dusty please.
- In water, oil, medical finrd, and organic solvent.

Please do not use component parts like rujbberwhich may contain sulfur(gasket packing, adhesive material, etc.)

Please note that any strong acidic or alcoholic elements could effect the silicon resin used in the LED device.

The heat and light released from the LED device, could generate halogen gas from the surrounding materials, which may have adverse impact on the module. Before using please consider carefully about this issue.

3 Heat radiation and Installation

If forward current (I_F) is applied to single-state module at any current, there is a risk of damaging LED or emitting smoke, due to increase in temperature.

Equip with specified heat radiator(heat sink), and avoid heart being stuffed inside the module. Material of substrate is alumina ceramic.IF installed inappropriately, trouble of insufficient heat radiation may occur, which may result in board cracks or lighting defects due to overheat. Please take particular notice for installation.

Refer to the following cautions while installing the LED device on heat sink.

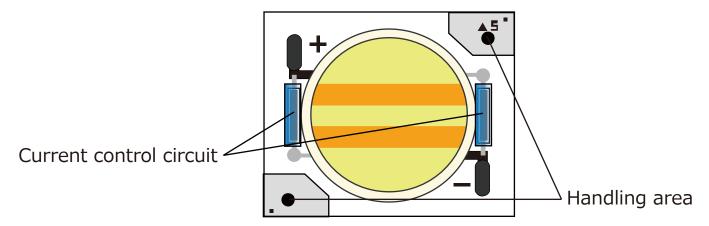
• Apply thermolysis adhesive, adhesive sheet or peculiar connector when mounted on heat radiator. In case of applying adhesive or adhesive sheet only, check the effectiveness and reliability before fixing. If LED comes off from heat radiator, unusual temperature rise entails hazardous phenomena including device deterioration, comming off of solder at leads, and emitting smoke, slong with LED device deffects.



- When LED device is mechanically fixed or locked, Please take into consideration regarding the method of attachment due to fail from stress.
- Please apply appropriate stress and design carefully, when fixing the LED device using holder. Any excessive or uneven stress could break LED device's substrate.
- Avoid convexly uneven boards. Convex board is subject to substrate cracking or debasement of heat release.
- It is recommented to apply adhesive or adhesive sheet with high thermal conductivity for radiation of heat effectively.
- Please take care about the influence of color change of adhesive or adhesive sheet in initial and long termperiod, which may affect light output or color due to change of reflectance from backside.
- Any excessive or uneven stress on the ceramic substrate could break the substrate. Please design such that,proper/uniform stress is applied on the substrate,when fixing the LED device using a holder.
- When fixing the LED device with a holder, please take note if any excessive or uneven stress is applied when pressing the substrate with holder. Due to this, the gap may arise between LED device and adhesive material, which may affect the heat dissipation of the device.
- Do not touch resin part including white resin part on the surface of LED.

 No light emission may occur due to damage of resin or cutting wire of LEDs by outer force.

 When using tweezers, please handle by side part of ceramic or the specified area shown below.



- The outer edges of the substrate may be uneven in some cases. Please avoid choosing these areas as fixing points, while designing for installation.
- In case of using heat radiation sheet or heat radiation adhesive, light reflection or absorption of these materials may influence the output of LED device. and hence careful consideration is required while choosing the radiation sheet ro adhesive.
- ④ Connecting method Use soldering for connections. Follow the conditioons mentioned below, to preserve the connection strength.
 - Use soldering iron with thermo controller(tip temperature 380℃, within 5 seconds per one place.



- Secure the solderwettability on whole solder pad and leads.
- During the soldering process, put the ceramic board on materials whose conductivity is poor enough not to radiate heat of soldering.
- Warm up(with using a heated plate) the substrate is recommended before soldering. (preheat condition: 100° C \sim 150° C, within 60sec)
- · Avoid touching any part of resin with soldering iron.
- This product is not designed for reflow and flow soldering.
- · Avoid such lead arrangement as applying stress to solder-applied area.
- · Please do not detach solder and make re-solder.
- Please solder evenly on each electrode.
- Please prevent flux from touching to resin.
- Do the soldering on stable stand. Avoid soldering on moving or vibrating objects.
- · Please avoid touching the soldering unit to resin.

Static electricity

This product is subject to static electricity, so take measures like wearing wrist band to cope with it. Install circuit protection device to drive circuit, if necessary.

6 Drive method

- Any reverse voltage cannot be applied to LEDs when they are in operation or not.

 Design a circuit so that any flow of reverse or forward voltage can not be applied to LEDs when they are out of operation.
- Module is composed of LEDs connected in both series and parallel.
 Constant voltage power supply runs off more than specified current amount due to lowered VF caused by temperature rise. Constant current power supply is recommended to drive.
- Be cautious while putting on/off the power supply,as excess current,excess voltage or reverse voltage may get injucted to the device in some cases.
- ⑦ Cleaning

Avoid cleaning, since LED device may be effected in some cases by cleaning.

® Color-tone variation

Chromaticity of this product is monitored by integrating sphere right after the operation.

Chromaticity varies depending on measuring method, light spread condition, or ambient temperature. Please verify your actual conditions before use.



9 Safety

- Looking directly at LEDs for a long time may result in hurting your eyes.
- In case that excess curent(over ratings) is supplied to the device, hazardous phenomena including abnormal heat generation, emitting smoke, or catching fire can caused.

 Take appropriate measures to excess current and voltage.
- In case of solder connecting method, there is a possibility of fatigue failure by heat.

 Please fix the leads in such case to protect from short circuit or leakage of electricity caused by contact.
- Please confirm the safety standards or regulations of application devices.
- Please be careful with substrate edges, that may injure your hands.

10 Other cautions

Guarantee covers the compliance to the quality standards mentioned in the specifications, however it does not cover the compatibility with application of the end-use, including assembly and usage environment.

In case any quality problems ocurred in the application of end-use, details will be separately discussed and determined between the parties hereto.

